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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10005633	FILING DATE 12/05/2001	CLASS 257 326	SUBCLASS 735	GAU 2521 3729	EXAMINER G. H. HILL
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**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A DIV OF 09/383,720 08/26/1999

** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 68665/2000 11/18/2000

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO A11-25124 D1
Foreign priority claimed 15 USC 119 conditions met verified and Acknowledged Examiners's initials	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	
TITLE : Microbeam assembly for integrated circuit interconnection to substrates		

U.S. DEPT. OF COMM/PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE		Total Claims	Print Claim for O.G. 7
Amount Due	Date Paid	DRAWING	
<input type="checkbox"/> TERMINAL DISCLAIMER		Sheets Drwg.	Figs. Drwg. Print Fig.
Assistant Examiner		Application Examiner	
Primary Examiner		PREPARED FOR ISSUE	
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